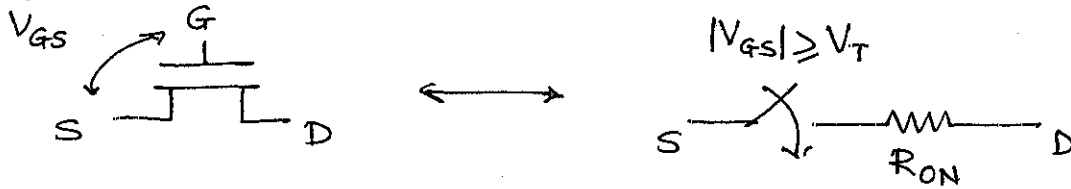
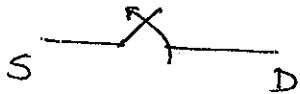
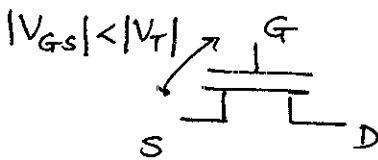


- MOS Transistor (Rabaey Chap 3, H+S chap 4)
- Basic Operation
- Modes of Operation
- Deep Sub-Micron (DSM) MOSFETs

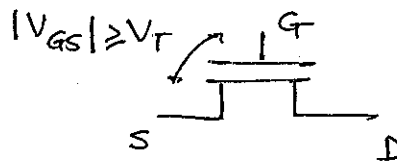
For digital circuits: A MOS transistor \longleftrightarrow A switch.



Switch OFF

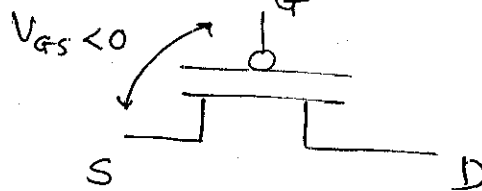
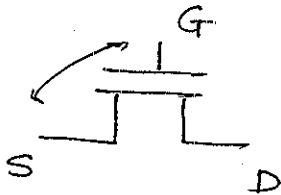


Switch ON



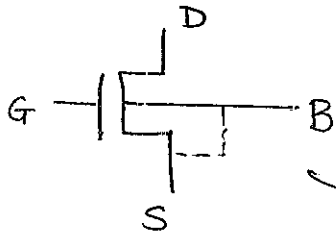
NMOS

$V_{gs} > 0$

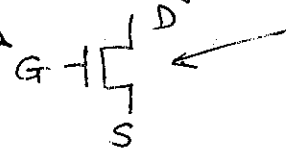


PMOS

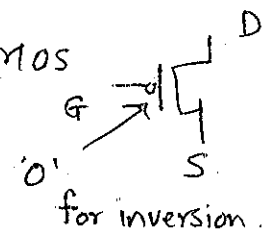
MOSFET is in reality a four terminal device



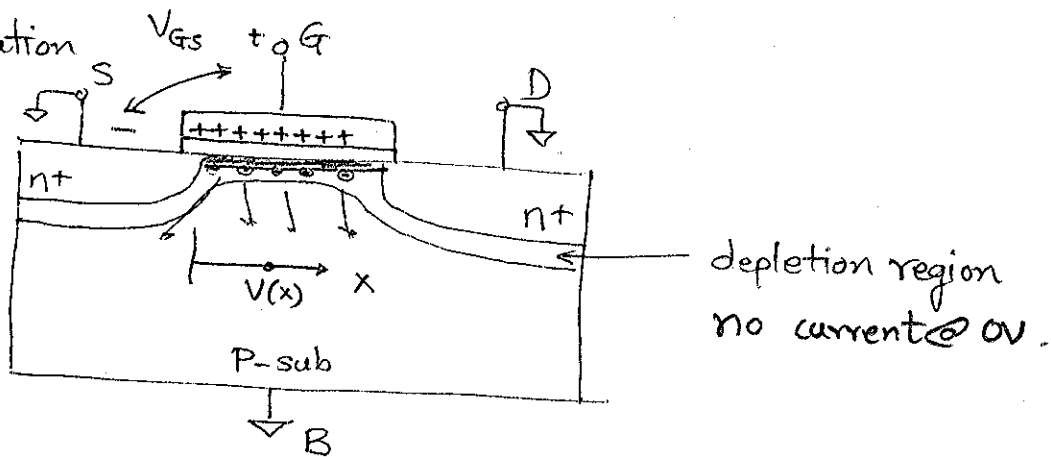
In most cases in digital design - body is tied to the source



Symbol for PMOS



Basic Operation



+ve charge on gate \rightarrow repels ~~near~~ mobile holes leaving +ve acceptor ions as keep increasing gate voltage, reaches a critical value. Surface 'inverts' n-type material \rightarrow onset of "strong inversion"

$$(2\phi_F)$$

$$\phi_F = 60 \text{ mV} \log_{10} \left(\frac{N_A}{n_i} \right)$$

further increase does not change the depletion layer depth, but results in additional electrons being drawn in from the n+ source \rightarrow continuous n+ channel is formed between S & D, whose conductivity is modulated by V_{GS}

$$|Q_{B,max}| = \sqrt{2qN_A \epsilon_{Si} |2\phi_F|} \leftarrow (2\phi_F + V_{SB})$$

$$\& V_{TN} = V_{FB} - 2\phi_F + \frac{1}{C_{ox}} |Q_{B,max}|$$

If we bias the bulk more negative than the source $V_{SB} > 0$

$$V_T = V_{T0} + \gamma \left(\sqrt{2\phi_F + V_{SB}} - \sqrt{2\phi_F} \right) \quad \gamma \approx 0.4 \sqrt{V}$$

V_T is positive for NMOS & negative for PMOS.

Resistive Operation (linear region)

$$Q_B = -C_{ox} (V_{GB} - V_T) \quad \text{MOS capacitor}$$

$$Q(x) = -C_{ox} (V_{GS} - V_T - V(x)) \quad C_{ox} = \frac{\epsilon_{ox}}{t_{ox}} \quad \frac{\text{Capacitance}}{\text{Area}}$$

$$I_D = v_n(x) \cdot Q(x) \cdot W$$

$$v_n(x) = \mu_n E = \mu_n \frac{\partial V}{\partial x}$$

$$I_D = \mu_n C_{ox} (V_{GS} - V_T - V(x)) \cdot \frac{\partial V(x)}{\partial x} \cdot W$$

$$\int I dx = \int \mu_n C_{ox} (V_{gs} - V_T - V(x)) dV \quad W$$

$$I_D L = \mu_n C_{ox} W \left((V_{gs} - V_T) V_{DS} - \frac{V_{DS}^2}{2} \right)$$

linear or resistive region. $V_{GS} > V_T$ V_{DS} very small

$$Q_B(x=0) = C_{ox} (V_{gs} - V_T)$$

$$Q_B(x=L) = C_{ox} (V_{gs} - V_T - V_{DS}) \quad [V_{GD} > V_{Tn}]$$

$$Q_{avg} = C_{ox} \left(V_{gs} - V_T - \frac{V_{DS}}{2} \right)$$

$$V_{GS} - V_{DS} > V_{Tn}$$

$$\text{Velocity } v = \mu_n E_{DS} = \mu_n \cdot \frac{V_{DS}}{L}$$

$$\text{or } V_{DS} < (V_{GS} - V_T)$$

$$I_D = v \cdot Q_{avg} \cdot W = \mu_n \cdot \frac{V_{DS}}{L} \cdot W \cdot C_{ox} \left(V_{gs} - V_T - \frac{V_{DS}}{2} \right)$$

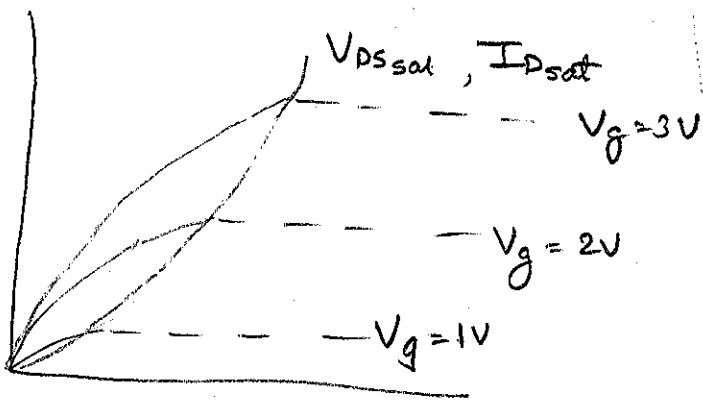
$$= \mu_n C_{ox} \frac{W}{L} \left[(V_{gs} - V_T) V_{DS} - \frac{V_{DS}^2}{2} \right]$$

$$V_{DS} < \underbrace{V_{GS} - V_T}_{V_{DSsat}}$$

V_{DSsat}

$$I_{Dsat} = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{gs} - V_T)^2$$

← substitute V_{DSsat}



saturation region

$$V_{DS} = V_{DSsat} = V_{gs} - V_T$$

$$Q_B(x=L) = 0 \text{ vanishes}$$

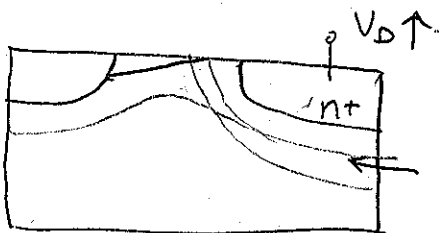
why do we get current

$$I_D = v \cdot Q \cdot W$$

very large

very very small

but has a limit → saturates



depletion region widens → reduces 'L'

→ channel length modulation (CLM)

$$V_{DS} > V_{DSsat} = V_{gs} - V_T$$

$$I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{gs} - V_T)^2 (1 + \lambda V_{DS})$$

Velocity saturation

When high horizontal E-fields reach a critical value E_{crit} velocity saturates due to scattering effects. (collisions)

$$V_{sat} = 10^5 \text{ m/s} \quad (E_{crit} = 1-5 \text{ V}/\mu\text{m})$$

$$L_{min} = 0.25 \mu\text{m} \quad \neq V_{crit} = 2 \text{ V!}$$

$$\mu_{el} = \frac{\mu_n E_{crit}}{1 + E/E_{crit}} = \frac{\mu_n}{1 + E/E_{crit}} \quad E \leq E_{crit}$$

$$= V_{sat}$$

$$E \geq E_{crit}$$

$$I_D = \frac{\mu_n}{1 + \frac{V_{DS}}{E_{crit} \cdot L}} \cdot \frac{V_{DS}}{L} \cdot W \cdot C_{ox} \left(V_{gs} - V_T - \frac{V_{DS}}{2} \right)$$

$$= K(V_{DS}) \mu_n C_{ox} \frac{W}{L} \left[(V_{gs} - V_T) V_{DS} - \frac{V_{DS}^2}{2} \right]$$

$$K = \frac{1}{1 + \frac{V_{DS}}{E_{crit} \cdot L}}$$

Now current at drain @ saturation $I_{Dsat} = V_{sat} \cdot C_{ox} W (V_{gs} - V_T - V_{DSAT})$

$$= K(V_{DS}) \cdot C_{ox} \mu_n \frac{W}{L} \cdot V_{DS} (V_{gs} - V_T - V_{DSAT})$$

$$V_{DSAT} = K(V_{GT}) \cdot V_{GT}$$

$$V_{GT} = V_{gs} - V_T \quad \text{not intuitive}$$

$$V_{DSAT} = L \cdot E_{crit} = \frac{L \cdot V_{sat}}{\mu_n}$$

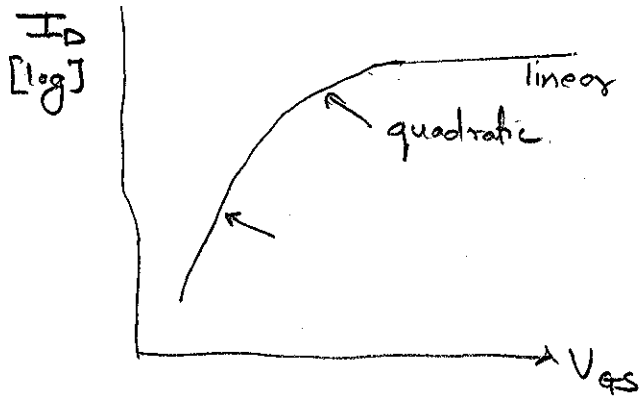
In resistive region equation remains unchanged $V_{DS} < V_{gs} - V_T$

$$I_{Dsat} = \mu_n C_{ox} \frac{W}{L} \left[(V_{gs} - V_T) V_{DSAT} - \frac{V_{DSAT}^2}{2} \right]$$

current saturates before any "pinch-off" occurs.

Sub-threshold Conduction

onset of strong inversion \Rightarrow ample carriers
does not mean no current can flow below V_T



$$V_{GS} < V_T$$

"parasitic $n^+ - p - n^+$

$$I_{DS} = I_S e^{\frac{V_{GS}}{n \cdot kT/q}}$$

undesirable
current flowing during OFF!

(inverse) rate of decline of current wrt. V_{GS} below $V_T \rightarrow$ quality of device

$$S = n \left(\frac{kT}{q} \right) \ln(10)$$

$$n=1 \quad S = 60 \text{ mV/decade}$$